



Material Content Data Sheet



Sales Product Name		BSZ110N06NS3 G		Issued		1. August 2018		
MA#		MA002325698						
Package		PG-TSDSON-8-2		Weight*		38.37 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.281	3.34	3.34	33385	33385
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		55	
	non noble metal	zinc	7440-66-6	0.008	0.02		218	
	non noble metal	iron	7439-89-6	0.168	0.44		4370	
wire	non noble metal	copper	7440-50-8	6.808	17.74	18.21	177422	182065
	non noble metal	copper	7440-50-8	0.036	0.09	0.09	943	943
encapsulation	organic material	carbon black	1333-86-4	0.035	0.09		906	
	plastics	epoxy resin	-	1.790	4.66		46650	
	inorganic material	silicondioxide	60676-86-0	15.553	40.55	45.30	405356	452912
leadfinish	non noble metal	tin	7440-31-5	0.387	1.01	1.01	10090	10090
plating	noble metal	silver	7440-22-4	0.963	2.51	2.51	25087	25087
solder	non noble metal	tin	7440-31-5	0.029	0.08		760	
	noble metal	silver	7440-22-4	0.036	0.10		950	
	non noble metal	lead	7439-92-1	1.393	3.63	3.81	36307	38017
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		28	
	non noble metal	zinc	7440-66-6	0.004	0.01		112	
	non noble metal	iron	7439-89-6	0.086	0.22		2247	
	non noble metal	copper	7440-50-8	3.501	9.12	9.35	91248	93635
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.002	0.00		49	
	non noble metal	zinc	7440-66-6	0.008	0.02		197	
	non noble metal	iron	7439-89-6	0.151	0.39		3933	
	non noble metal	copper	7440-50-8	6.127	15.97	16.38	159687	163866
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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